

[METHOD FOR PREVENTING CORROSION IN THE FABRICATION OF INTEGRATED CIRCUITS]

Abstract of Disclosure

An improved post-metal-plasma-etching wafer cleaning process includes providing a wafer having a naked metal structure thereon, dipping the wafer into a first cleaning vessel having a volume of basic solution therein, and after dipping the wafer in the first cleaning vessel, the wafer is then transferred into a second cleaning vessel to perform at least one cycle of a hot QDR cleaning process.

Patented by USPTO

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